



SC-1P4-GG



SC-8P1-GT

SC, T SERIES

# MACHINED TERMINALS & SOCKETS

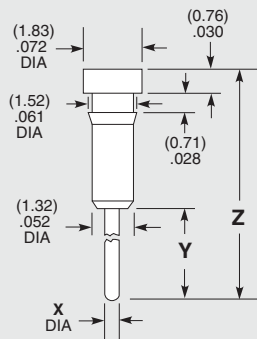
## SPECIFICATIONS

### SC

**Contact:** BeCu  
**Shell:** Brass  
**-GG Plating:**  
 30 μ" (0.76 μm) Au over  
 50 μ" (1.27 μm) Ni on contact;  
 10 μ" (0.25 μm) Au over  
 50 μ" (1.27 μm) Ni on shell  
**-GT Plating:**  
 30 μ" (0.76 μm) Au over  
 50 μ" (1.27 μm) Ni on contact;  
 Sn over 50 μ" (1.27 μm) Ni  
 on shell  
**-TT Plating:**  
 Sn over 50 μ" (1.27 μm)  
 Ni on contact; Sn over  
 50 μ" (1.27 μm) Ni on shell  
**-ST Plating:**  
 10 μ" (0.25 μm) Au over  
 50 μ" (1.27 μm) Ni on contact;  
 Sn over 50 μ" (1.27 μm)  
 Ni on shell  
**Lead DIA Accepted:**  
 (0.38 mm) .015" to  
 (0.56 mm) .022" and  
 most IC leads

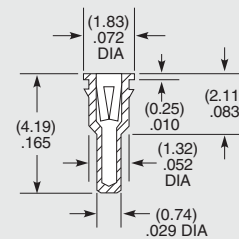
## SC-1P1-, SC-6P1-

Part No.	X DIA	Y ±.010	Z ±.015
SC-1P1-	(0.51) .020	(3.18) .125	(7.62) .300
SC-6P1-	(0.51) .020	(4.57) .180	(8.89) .350



Insertion Depth (SC-1P1, SC-6P1) = (2.41 mm) .95" to (3.68 mm) .145"  
 Plating Available (SC-1P1) = GG, GT, TT, ST  
 Plating Available (SC-6P1) = GG, GT

## SC-8P1



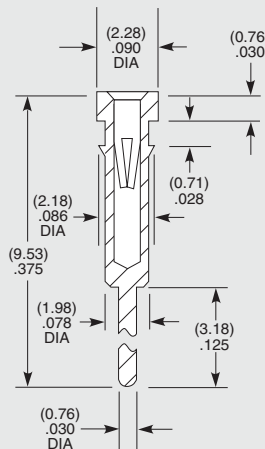
Insertion Depth = (2.16 mm) .085" to .140" (3.56 mm)  
 Lead DIA Accepted: (0.41 mm) .016" to (0.51 mm) .020"  
 Plating Available = GG, GT, TT

## SPECIFICATIONS

### SC-1P4

**Contact:** BeCu  
**Shell:** Brass  
**-GG Plating:**  
 20 μ" (0.51 μm) Au over  
 50 μ" (1.27 μm) Ni on contact  
**-GT Plating:**  
 20 μ" (0.51 μm) Au over  
 50 μ" (1.27 μm) Ni on contact  
**Insertion Force:**  
 6.5 oz (1.81 N) avg,  
 13 oz (3.62 N) max  
 (.032" (0.81 mm) DIA probe)  
**Withdrawal Force:**  
 3 oz (0.83 N) avg,  
 2 oz (0.56 N) min  
 (.032" (0.81 mm) DIA probe)

## SC-1P4-

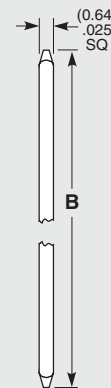


### RECOMMENDED PC HOLE SIZE:

LEAD SIZE	HOLE SIZE
(0.46) .018 DIA	(0.61) .024 DIA
(0.51) .020 DIA	(0.66) .026 DIA
(0.64) .025 DIA	(0.79) .031 DIA
(0.76) .030 DIA	(0.91) .036 DIA
(0.89) .035 DIA	(1.04) .041 DIA
(1.14) .045 DIA	(1.30) .051 DIA
(1.32) .052 DIA	(1.47) .058 DIA
(0.46) .018 SQ	(0.76) .030 DIA
(0.64) .025 SQ	(1.02) .040 DIA
(1.14) .045 SQ	(1.75) .069 DIA
(0.20) .008 x (0.71) .028	(0.89) .035 DIA
(0.25) .010 x (0.51) .020	(0.71) .028 DIA
(0.41) .016 x (0.51) .020	(0.79) .031 DIA
(0.41) .016 x (0.61) .024	(0.89) .035 DIA
(0.41) .016 x (0.79) .031	(1.04) .041 DIA

Insertion Depth = (4.45 mm) .175" to (5.46 mm) .215"  
 Lead DIA Accepted = (0.81 mm) .032" to (0.97 mm) .038"  
 Plating Available = GG, GT

## T-1S6-



PART NO.	B
T-1S6-07-X-2	(10.92) .430
T-1S6-08-X-2	(13.46) .530
T-1S6-09-X-2	(18.54) .730
T-1S6-10-X-2	(21.08) .830
T-1S6-11-X-2	(23.62) .930
T-1S6-12-X-2	(26.16) 1.030
T-1S6-13-X-2	(31.24) 1.230
T-1S6-14-X-2	(36.32) 1.430
T-1S6-15-X-2	(16.00) .630
T-1S6-16-X-2	(11.30) .445
T-1S6-17-X-2	(12.19) .480
T-1S6-18-X-2	(7.62) .300
T-1S6-19-X-2	(33.78) 1.330
T-1S6-20-X-2	(28.70) 1.130
T-1S6-21-X-2	(8.51) .335

Pins are supplied on a bandolier.

Material: Phosphor Bronze  
 X = Plating option (specify G or T)  
 -G = 10 μ" (0.25 μm) Gold on (4.19 mm) .165"  
 contact area. Gold flash on balance  
 -T = 200 μ" (5.08 μm) Tin

## SPECIFICATIONS

### T-1S6

T Series is available with a choice of Gold or Tin plating. Add -G or -T as a suffix to the part number shown.

**-G Plating:**  
 Au over 50 μ" (1.27 μm) Ni  
**-T Plating:**  
 Sn over 50 μ" (1.27 μm) Ni or 100 μ" (2.54 μm) Cu

**Note:**  
 Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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All parts within this catalog are built to Samtec's specifications.  
 Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.